

MM5483 Liquid Crystal Display Driver

Check for Samples: MM5483

FEATURES

- Serial Data Input
- Serial Data Output
- Wide Power Supply Operation
- TTL Compatibility
- 31 Segment Outputs
- Alphanumeric and Bar Graph Capability
- Cascade Capability

APPLICATIONS

- COPS[™] or Microprocessor Displays
- Industrial Control Indicator
- Digital Clock, Thermometer, Counter, Voltmeter
- Instrumentation Readouts
- Remote Displays

Block Diagram

DESCRIPTION

The MM5483 is a monolithic integrated circuit utilizing CMOS metal-gate low-threshold enhancement mode devices. It is available in a 40-pin PDIP package. The chip can drive up to 31 segments of LCD and can be cascaded to increase this number. This chip is capable of driving a $4\frac{1}{2}$ -digit 7-segment display with minimal interface between the display and the data source.

The MM5483 stores the display data in latches after it is latched in, and holds the data until another load pulse is received.

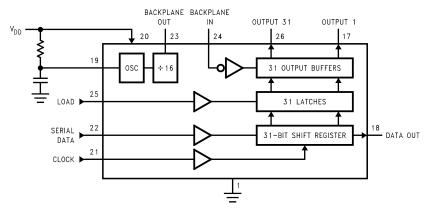


Figure 1. MM5483 Block Diagram

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Connection Diagrams

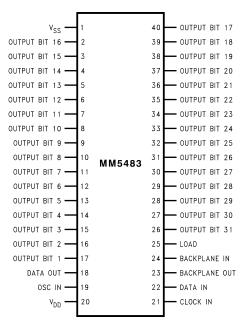


Figure 2. Dual-In-Line Package Top View See Package Number NFJ0040A

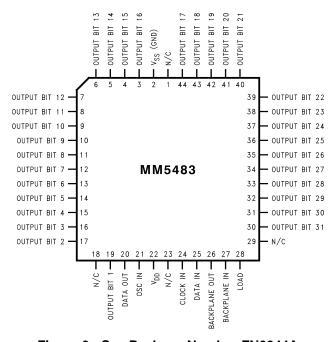


Figure 3. See Package Number FN0044A



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings (1)(2)

Voltage at Any Pin	V_{SS} to V_{SS} +10V
Operating Temperature	−40°C to +85°C
Storage Temperature	−65°C to +150°C
Power Dissipation	300 mW at +85°C 350 mW at +25°C
Junction Temperature	+150°C
Lead Temperature (Soldering, 10 seconds)	300°C

^{(1) &}quot;Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be ensured. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" specifies conditions of device operation.

DC Electrical Characteristics

 T_A within operating range, $V_{DD} = 3.0V$ to 10V, $V_{SS} = 0V$, unless otherwise specified

Parameter	Conditions	Min	Тур	Max	Units	
Power Supply		3.0		10	V	
Average Supply Current I	All Outputs Bits = Open, Data Out = Open, BP_Out = Open, Clock In = 0V, Data In = 0V, Data Load = 0V, Osc In = 0V, BP_In = 32Hz					
Average Supply Current, I _{DD}	$V_{DD} = 3.0V$		1.5	2.5	μA	
	$V_{DD} = 5.0V$			10	μA	
	$V_{DD} = 10.0V$			40	μA	
Input Voltage Levels Logic "0" Logic "1" Logic "0" Logic "1"	Load, Clock, Data $V_{DD} = 5.0V$ $V_{DD} = 5.0V$ $V_{DD} = 5.0V$ $V_{DD} = 3.0V$ $V_{DD} = 3.0V$	2.4		0.9 0.4	V V V	
Output Current Levels ⁽¹⁾ Segments and Data Out Sink Source	V _{DD} = 3.0V, V _{OUT} = 0.3V V _{DD} = 3.0V, V _{OUT} = 2.7V	20 20			μΑ μΑ	
BP Out Sink BP Out Source	$V_{DD} = 3.0V, V_{OUT} = 0.3V$ $V_{DD} = 3.0V, V_{OUT} = 2.7V$	320 320			μA μA	

⁽¹⁾ Output offset voltage is ± 50 mV with $C_{SEGMENT} = 250$ pF, $C_{BP} = 8750$ pF.

AC Electrical Characteristics

 $V_{DD} \ge 4.7V$, $V_{SS} = 0V$ unless otherwise specified

Symbol	Parameter	Min	Тур	Max	Units
$f_{\mathbb{C}}$	Clock Frequency, V _{DD} = 3V			500	kHz
t _{CH}	Clock Period High	⁽¹⁾⁽²⁾ 500			ns
t _{CL}	Clock Period Low	500			ns
t _{DS}	Data Set-Up before Clock	300			ns
t _{DH}	Data Hold Time after Clock	100			ns
t_{LW}	Minimum Load Pulse Width	500			ns
t_{LTC}	Load to Clock	400			ns
t _{CDO}	Clock to Data Valid		400	750	ns

AC input waveform specification for test purpose: t_r ≤ 20 ns, t_f ≤ 20 ns, f = 500 kHz, 50% ± 10% duty cycle.

Product Folder Links: MM5483

⁽²⁾ If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.

⁽²⁾ Clock input rise and fall times must not exceed 300 ms.



FUNCTIONAL DESCRIPTION

A block diagram for the MM5483 is shown in Figure 1 and a package pinout is shown in Figure 3. Figure 4 shows a possible 3-wire connection system with a typical signal format for Figure 4. Shown in Figure 5, the load input is an asynchronous input and lets data through from the shift register to the output buffers any time it is high. The load input can be connected to V_{DD} for 2-wire control as shown in Figure 6. In the 2-wire control mode, 31 bits (or less depending on the number of segments used) of data are clocked into the MM5483 in a short time frame (with less than 0.1 second there probably will be no noticeable flicker) with no more clocks until new information is to be displayed. If data was slowly clocked in, it can be seen to "walk" across the display in the 2-wire mode. An AC timing diagram can be seen in Figure 7. It should be noted that data out is not a TTL-compatible output.

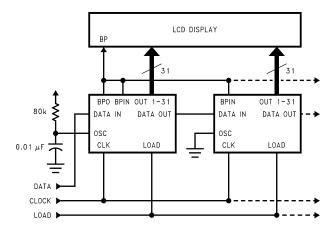


Figure 4. Three-Wire Control Mode

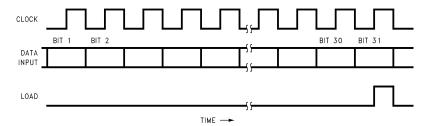


Figure 5. Data Format Diagram

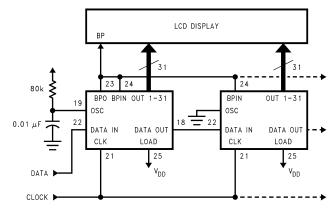


Figure 6. Two-Wire Control Mode

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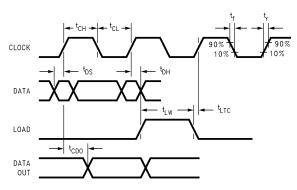


Figure 7. Timing Diagram

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SNLS368E - JULY 2000-REVISED MARCH 2013



REVISION HISTORY

Cł	nanges from Revision D (March 2013) to Revision E	Pag	E
•	Changed layout of National Data Sheet to TI format		Ę





20-Mar-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
MM5483N	ACTIVE	PDIP	NFJ	40	9	TBD	Call TI	Call TI	-40 to 85	MM5483N	Samples
MM5483N/NOPB	ACTIVE	PDIP	NFJ	40	9	Green (RoHS & no Sb/Br)	SN	Level-1-NA-UNLIM	-40 to 85	MM5483N	Samples
MM5483V	ACTIVE	PLCC	FN	44	25	TBD	Call TI	Call TI	-40 to 85	MM5483V	Samples
MM5483V/NOPB	ACTIVE	PLCC	FN	44	25	Green (RoHS & no Sb/Br)	SN	Level-3-245C-168 HR	-40 to 85	MM5483V	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

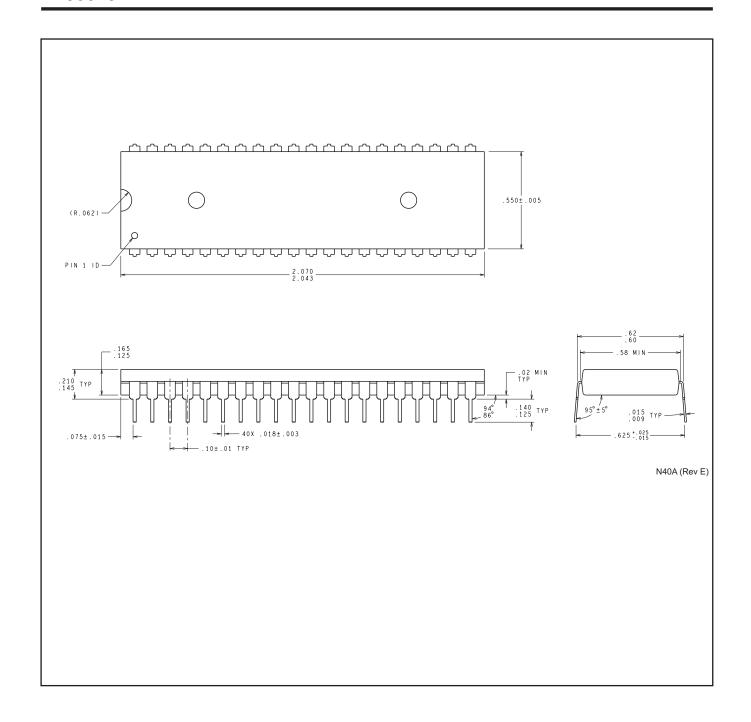
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.



FN (S-PQCC-J**)

20 PIN SHOWN

PLASTIC J-LEADED CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-018



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